



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Film Chip Capacitor

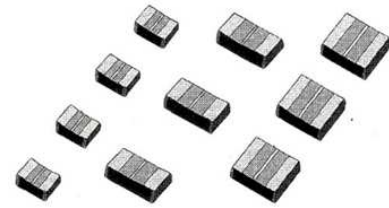
Type: **ECP(U)B**

*Production volume is currently limited.
Please consult with Panasonic about

Stacked dielectric with inner electrode and simple mold-less construction

► Features

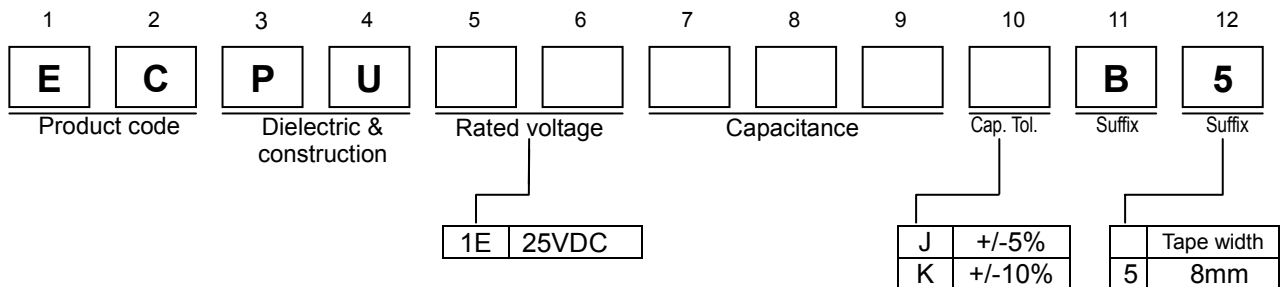
- Low ESR
- Max. capacitance values 1.0μF
- Smallest package size in film capacitors 3216/1.0μF
- For reflow soldering



► Recommended Applications

- Noise suppressor
- Coupling circuit for Audio

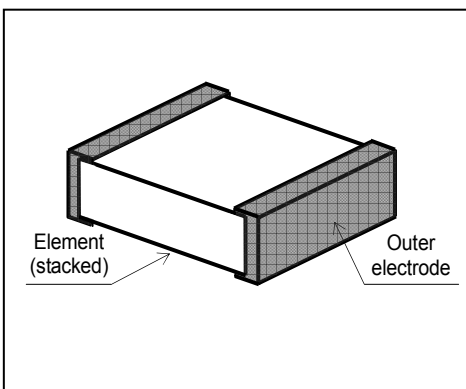
► Explanation of Part Numbers



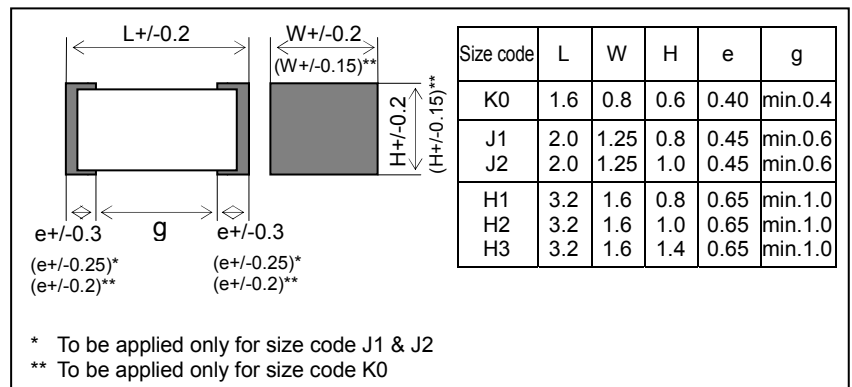
► Specification

Category temp.range (Including temperature-rise on unit surface)	-40 to +105 degree C
Rated voltage	25VDC (Derating of rated voltage by 2.5%/degree C more than 85 degree C)
Capacitance range	0.0068μF to 1.0μF (E12)
Capacitance tolerance	+/-5%(J), +/-10%(K)
Withstand voltage	Between terminals : Rated volt. (VDC)X150% , 1min
Dissipation factor	1.5% max. (20 degree C , 1kHz)
Insulation resistance	0.0068μF - 0.33μF : 1000MΩ min. (20 degree C , 25VDC , 60s) 0.39μF - 1.0μF : 300MΩ • μFmin. (20 degree C , 25VDC , 60s)
Soldering conditions	Reflow soldering : 260 degree C max. and 90s max. at more than 220 degree C (Temp. at cap. Surface)

► Construction



► Dimensions in mm (not to scale)



► Taping Specification for Automatic Mounting

Refer to the taping specifications.

Design, Specifications are subject to change without notice. Ask factory for technical specifications before purchase and/or use. Whenever a doubt safety arises from this product, please inform us immediately for technical consultation without fail.

► Rating , Dimensions & quantity / Reel

■ Capacitance tolerance : +/- 5%(J), +/- 10%(K),

Cap. (μ F)	Rated volt. 25VDC					
	Part No.	Dimensions (mm)			Size code	Q'ty
		L	W	H		
0.0068	ECPU1E682()B5	1.6	0.8	0.6	K0	4000
0.0082	ECPU1E822()B5	1.6	0.8	0.6	K0	
0.01	ECPU1E103()B5	1.6	0.8	0.6	K0	
0.012	ECPU1E123()B5	1.6	0.8	0.6	K0	
0.015	ECPU1E153()B5	1.6	0.8	0.6	K0	
0.018	ECPU1E183()B5	1.6	0.8	0.6	K0	
0.022	ECPU1E223()B5	1.6	0.8	0.6	K0	
0.027	ECPU1E273()B5	1.6	0.8	0.6	K0	
0.033	ECPU1E333()B5	1.6	0.8	0.6	K0	
0.039	ECPU1E393()B5	1.6	0.8	0.6	K0	
0.047	ECPU1E473()B5	2.0	1.25	0.8	J1	3000
0.056	ECPU1E563()B5	2.0	1.25	0.8	J1	
0.068	ECPU1E683()B5	2.0	1.25	0.8	J1	
0.082	ECPU1E823()B5	2.0	1.25	0.8	J1	
0.1	ECPU1E104()B5	2.0	1.25	1.0	J2	
0.12	ECPU1E124()B5	2.0	1.25	1.0	J2	
0.15	ECPU1E154()B5	2.0	1.25	1.0	J2	
0.18	ECPU1E184()B5	3.2	1.6	0.8	H1	
0.22	ECPU1E224()B5	3.2	1.6	0.8	H1	
0.27	ECPU1E274()B5	3.2	1.6	0.8	H1	
0.33	ECPU1E334()B5	3.2	1.6	0.8	H1	
0.39	ECPU1E394()B5	3.2	1.6	0.8	H1	
0.47	ECPU1E474()B5	3.2	1.6	1.0	H2	
0.56	ECPU1E564()B5	3.2	1.6	1.0	H2	
0.68	ECPU1E684()B5	3.2	1.6	1.4	H3	
0.82	ECPU1E824()B5	3.2	1.6	1.4	H3	2000
1.0	ECPU1E105()B5	3.2	1.6	1.4	H3	

► Example for Land Dimensions (mm)

Size code	Land dimensions Reflow soldering		
	A	B	C
K0	0.6	2.0	0.7
J1,J2	0.8	2.4	1.1
H1,H2,H3	1.8	3.6	1.4